

# FDPF2710T

## N-Channel PowerTrench® MOSFET 250 V, 25 A, 42.5 mΩ

### Features

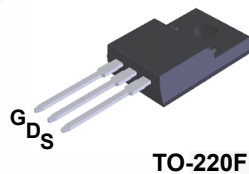
- $R_{DS(on)} = 36.3 \text{ m}\Omega$  (Typ.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 25 \text{ A}$
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low  $R_{DS(on)}$
- High Power and Current Handling Capability
- RoHS Compliant

### Description

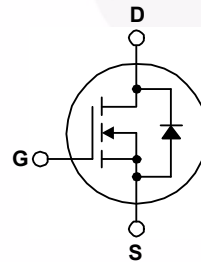
This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

### Applications

- Consumer Appliances
- Synchronous Rectification



TO-220F



### Absolute Maximum Ratings

Symbol	Parameter	FDPF2710T	Unit
$V_{DS}$	Drain-Source Voltage	250	V
$V_{GS}$	Gate-Source voltage	$\pm 30$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	25
		- Continuous ( $T_C = 100^\circ\text{C}$ )	18.8
$I_{DM}$	Drain Current - Pulsed (Note 1)	100	A
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	145	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	- Derate above $25^\circ\text{C}$	62.5
			0.5
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FDPF2710T	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.0	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	$^\circ\text{C}/\text{W}$

**Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDPF2710T	FDPF2710T	TO-220F	Tube	N/A	50 units

**Electrical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

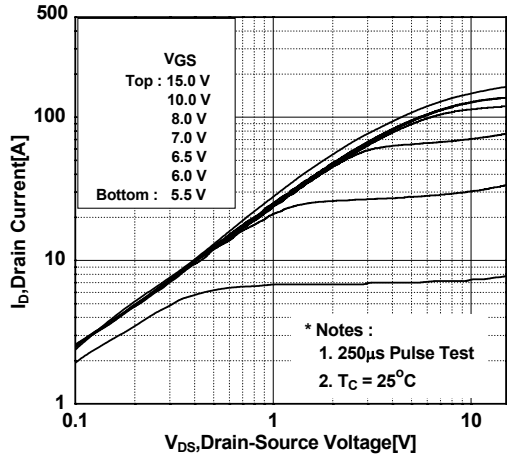
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ\text{C}$	250	--	--	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$ , Referenced to $25^\circ\text{C}$	--	0.25	--	$V/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 250V, V_{GS} = 0V$ $V_{DS} = 250V, V_{GS} = 0V, T_C = 125^\circ\text{C}$	--	--	10 500	$\mu A$ $\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	3.0	3.9	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 25A$	--	36.3	42.5	$m\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 10V, I_D = 25A$	--	63	--	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$	--	5470	7280	pF
$C_{oss}$	Output Capacitance		--	426	567	pF
$C_{rss}$	Reverse Transfer Capacitance		--	97	146	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 125V, I_D = 50A$ $V_{GS} = 10V, R_{GEN} = 25\Omega$	--	80	170	ns
$t_r$	Turn-On Rise Time		--	252	514	ns
$t_{d(off)}$	Turn-Off Delay Time		--	112	234	ns
$t_f$	Turn-Off Fall Time		(Note 4)	--	154	318
$Q_g$	Total Gate Charge	$V_{DS} = 125V, I_D = 50A$ $V_{GS} = 10V$	--	78	101	nC
$Q_{gs}$	Gate-Source Charge		--	34	--	nC
$Q_{gd}$	Gate-Drain Charge		(Note 4)	--	18	--
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		--	--	25	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		--	--	150	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 25A$	--	--	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_S = 50A$	--	163	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt = 130A/\mu s$	--	1.3	--	$\mu C$

**Notes:**

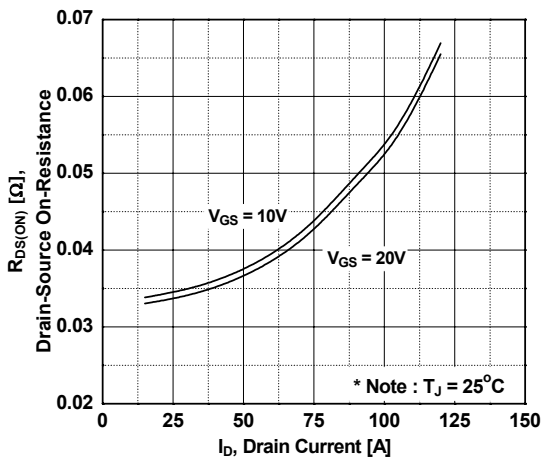
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $L = 1\text{mH}, I_{AS} = 17A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 50A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

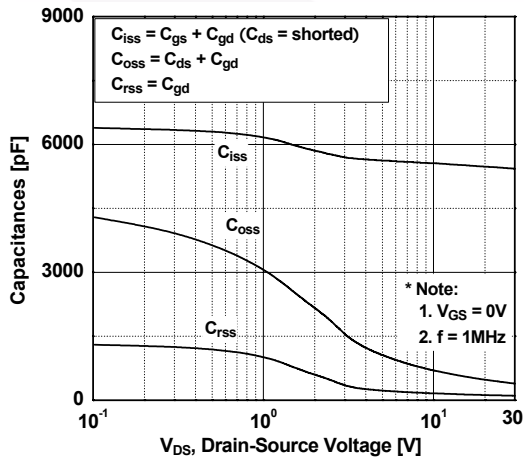
**Figure 1. On-Region Characteristics**



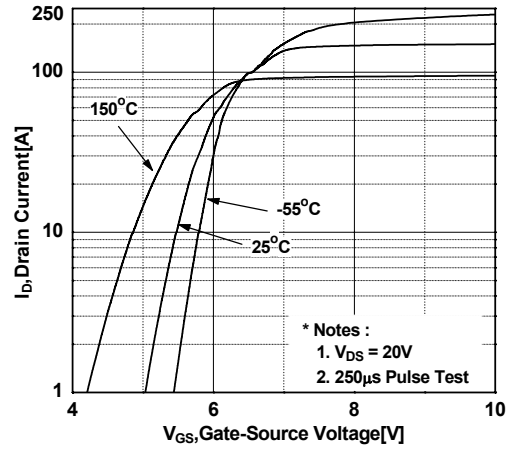
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



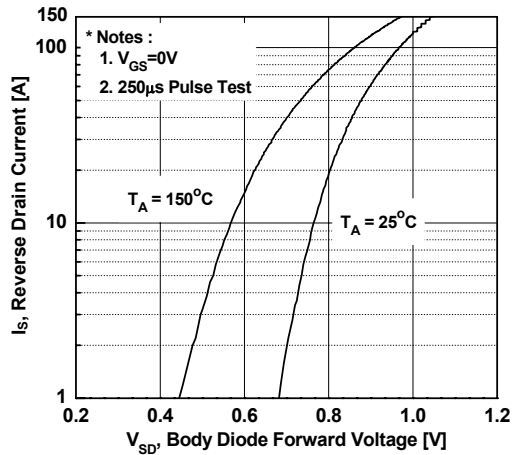
**Figure 5. Capacitance Characteristics**



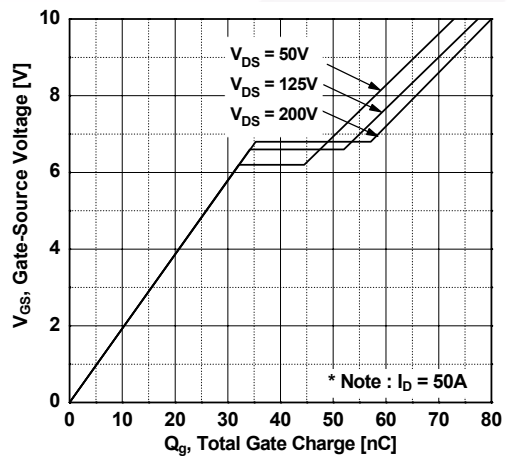
**Figure 2. Transfer Characteristics**



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

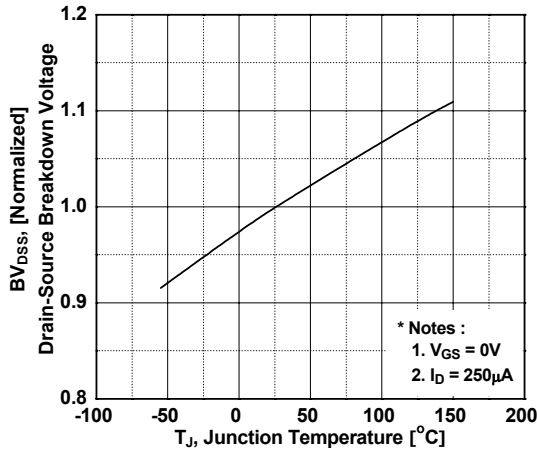


**Figure 6. Gate Charge Characteristics**

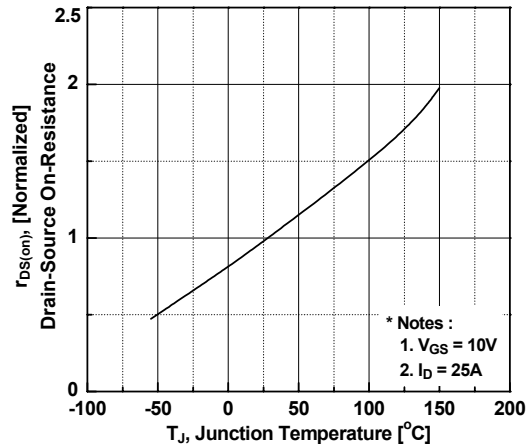


**Typical Performance Characteristics (Continued)**

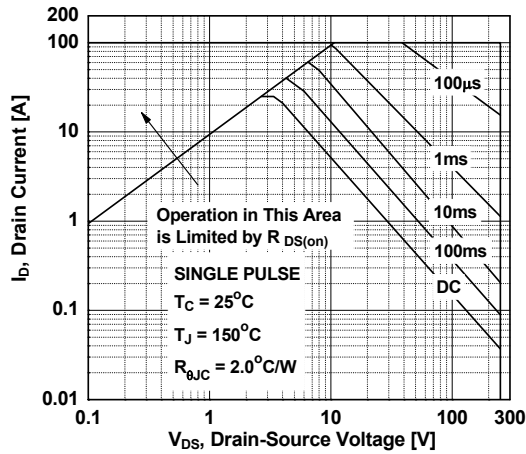
**Figure 7. Breakdown Voltage Variation vs. Temperature**



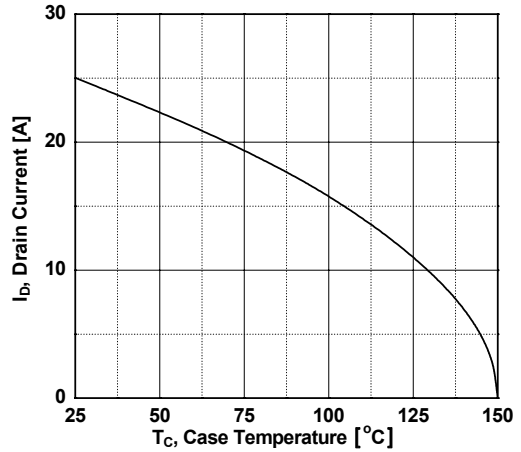
**Figure 8. On-Resistance Variation vs. Temperature**



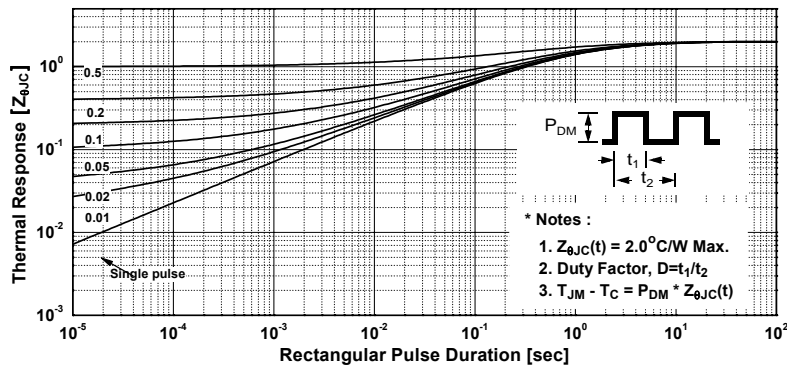
**Figure 9. Maximum Safe Operating Area**



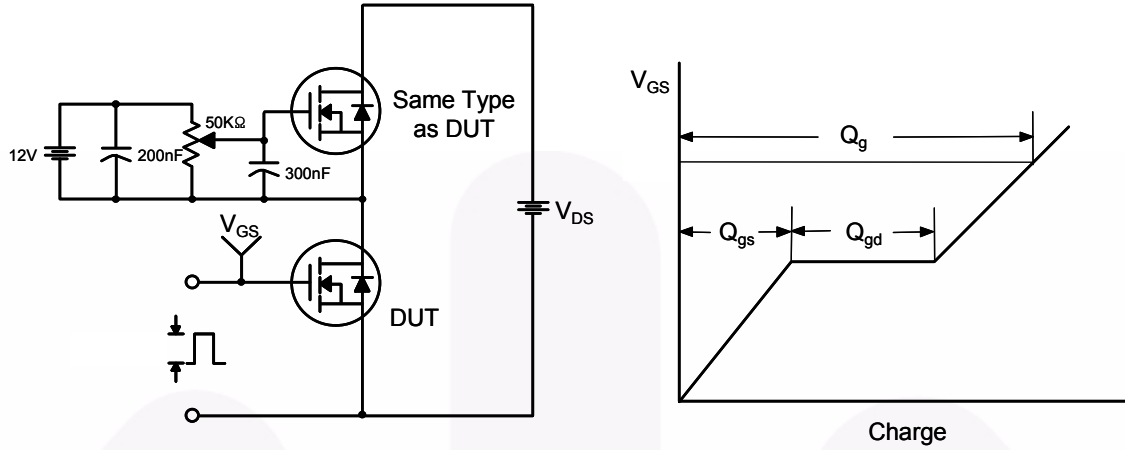
**Figure 10. Maximum Drain Current vs. Case Temperature**



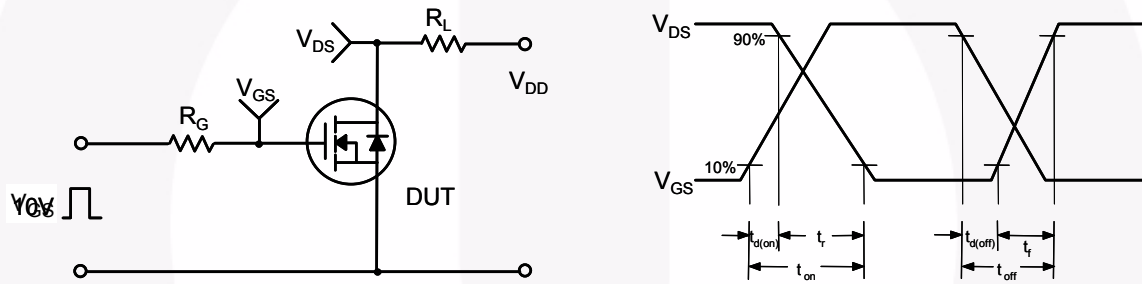
**Figure 11. Transient Thermal Response Curve**



**Figure 12. Gate Charge Test Circuit & Waveform**



**Figure 13. Resistive Switching Test Circuit & Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

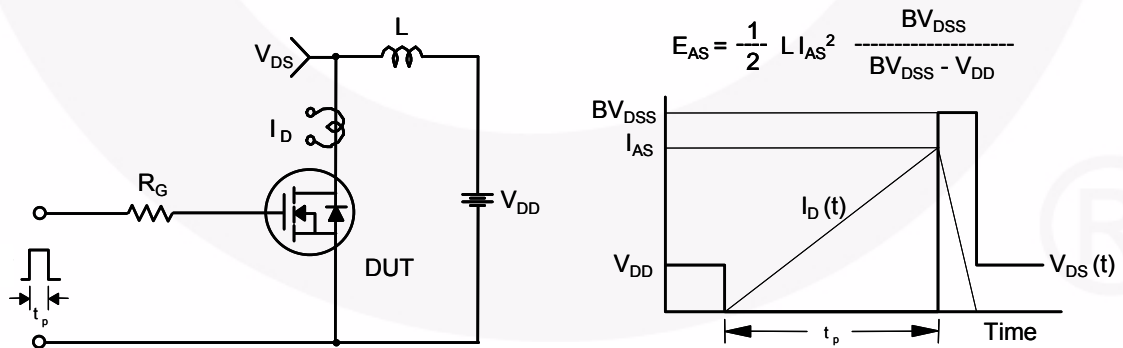
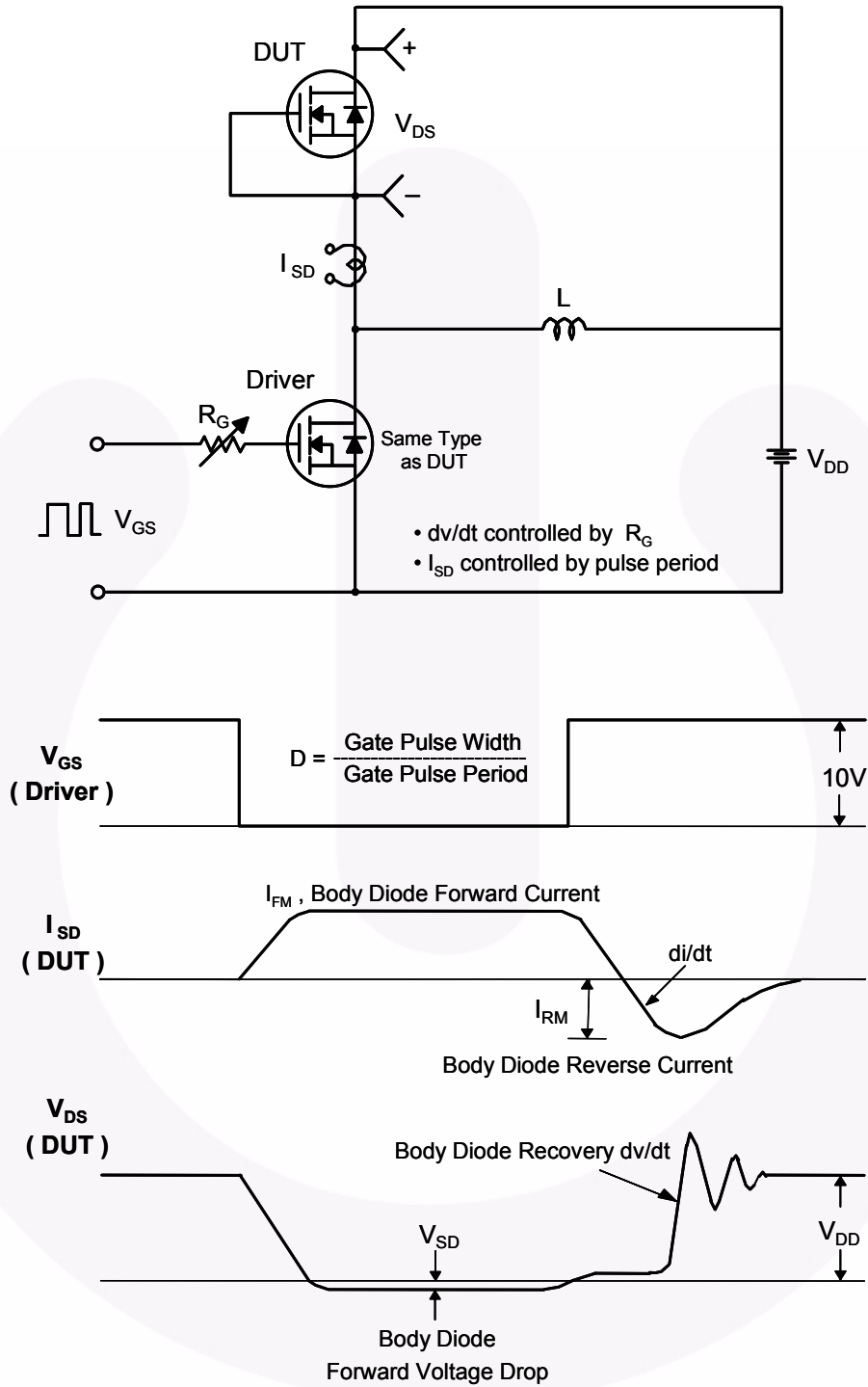
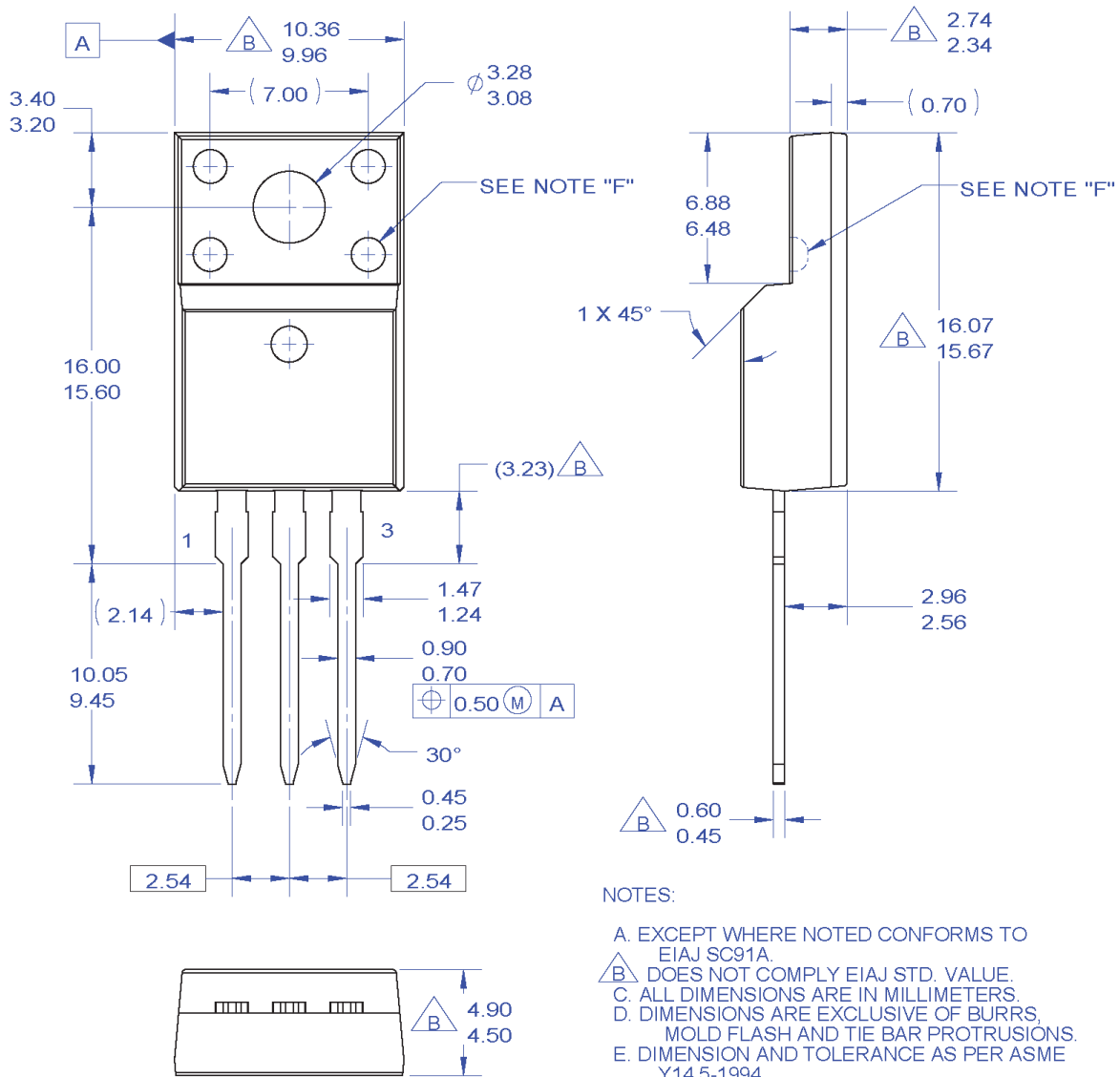


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



## Mechanical Dimensions

### TO-220F 3L



#### NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B. DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. OPTION 1 - WITH SUPPORT PIN HOLE.  
OPTION 2 - NO SUPPORT PIN HOLE.
- G. DRAWING FILE NAME: TO220M03REV3

**Figure 16. TO220, Molded, 3LD, Full Pack, EIAJ SC91, Straight Lead**

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Dimension in Millimeters



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| AX-CAP®*   | FRFET®  | PowerXS™  |  SYSTEM GENERAL®* |
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| FETBench™  | OPTOLOGIC®                                      | SyncFET™  | VoltagePlus™   |
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